

FIG. 1 is a schematic diagram of a device 100. The device 100 includes a substrate 110, a first layer 120, a second layer 130, and a third layer 140. The first layer 120 is disposed on the substrate 110, and the second layer 130 is disposed on the first layer 120. The third layer 140 is disposed on the second layer 130. The first layer 120 includes a plurality of openings 124. The second layer 130 includes a plurality of openings 135. The third layer 140 includes a plurality of openings 140. The device 100 is configured to provide a plurality of openings 124, 135, and 140.

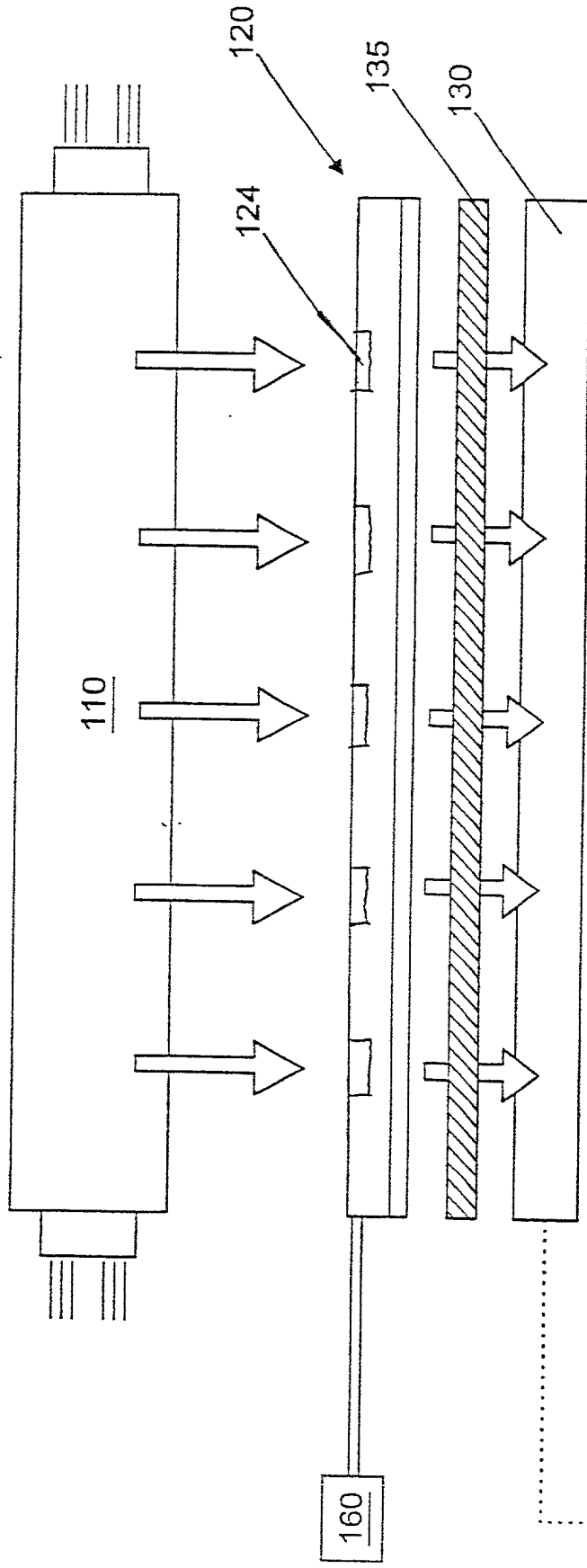


FIG. 1

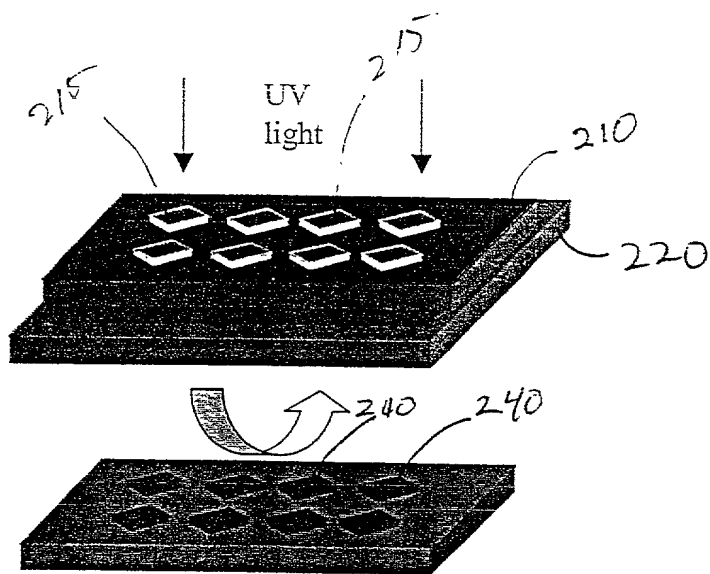


FIG. 2

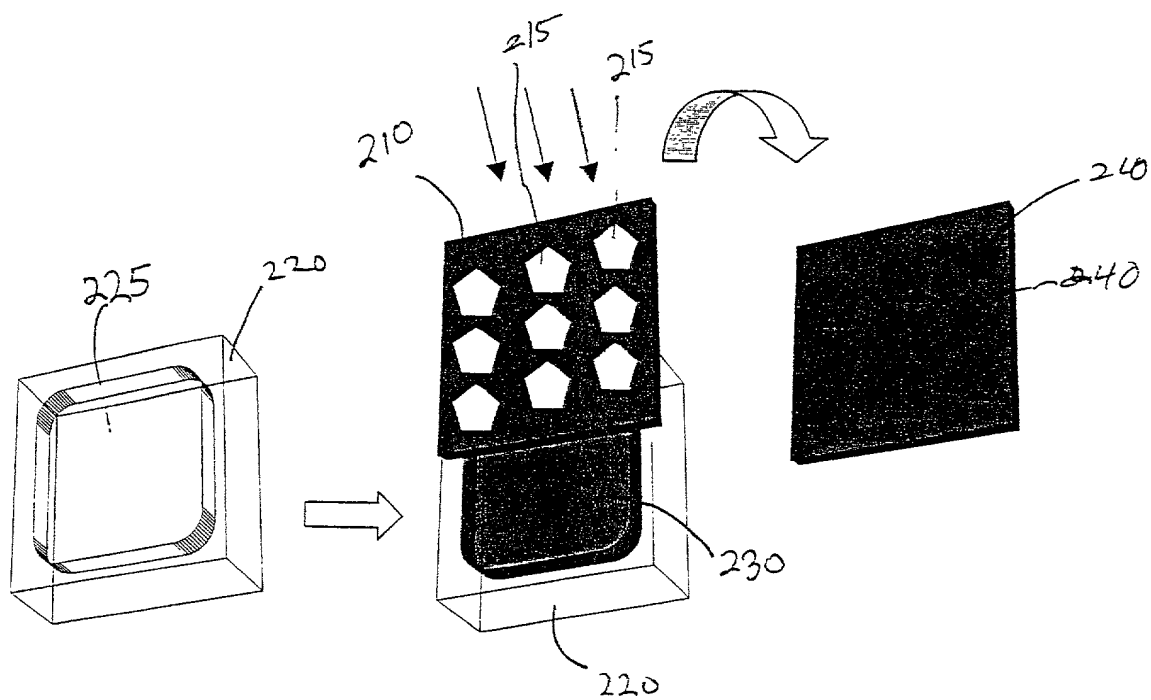


FIG. 3

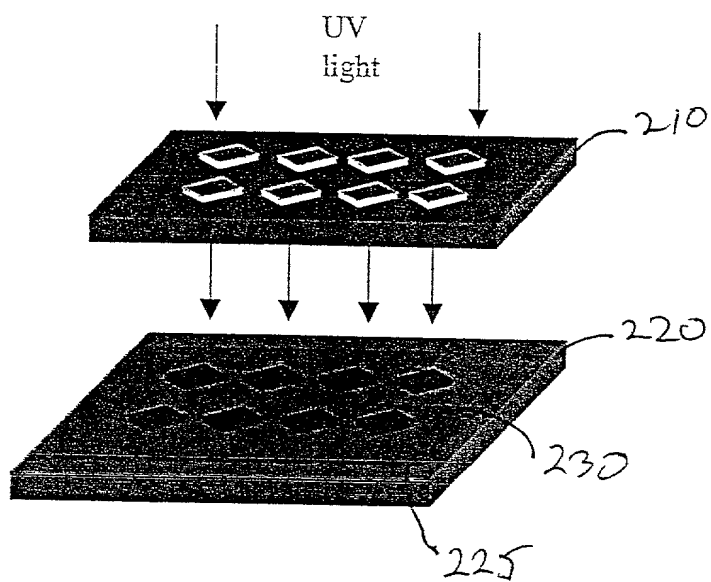


FIG. 4

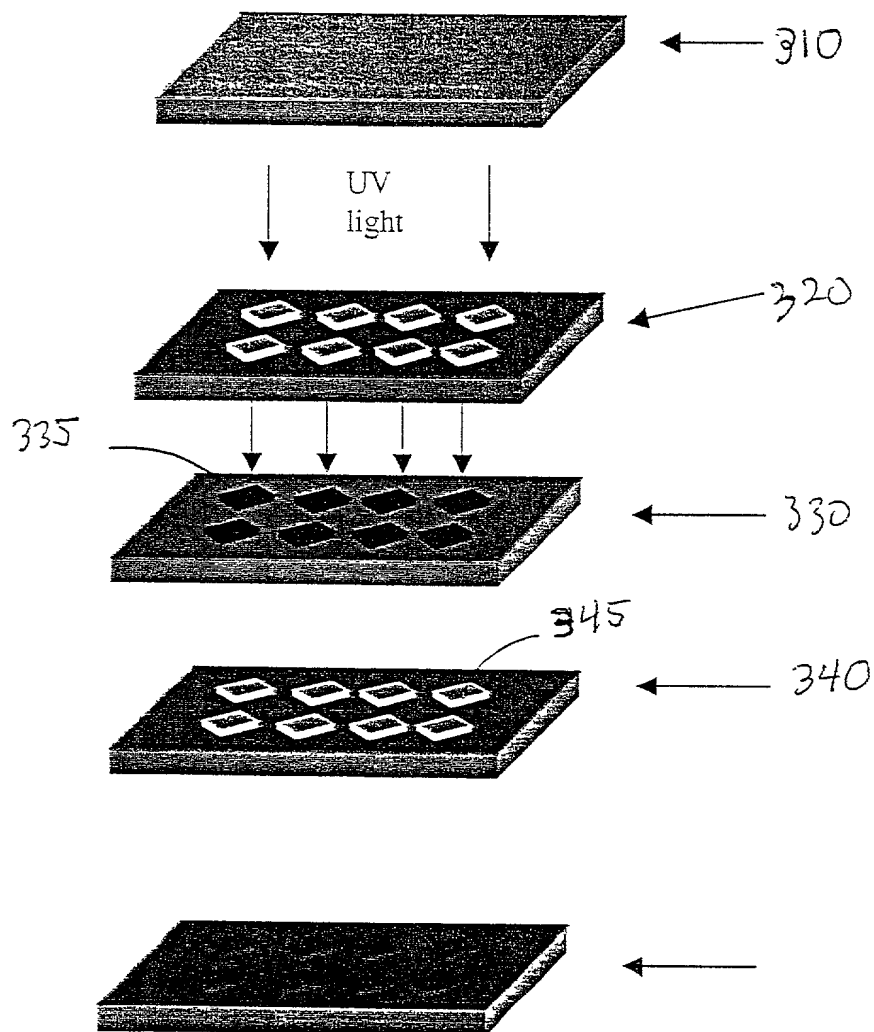


FIG. 5

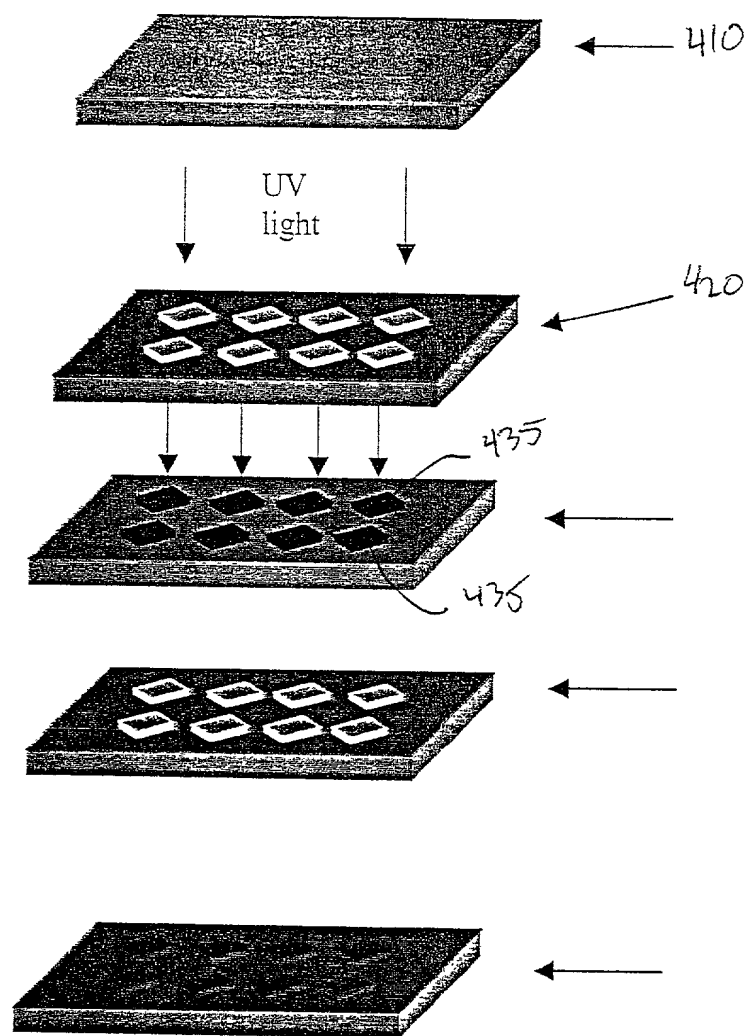


FIG. 6

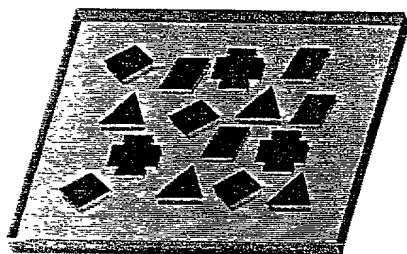


Fig. 7

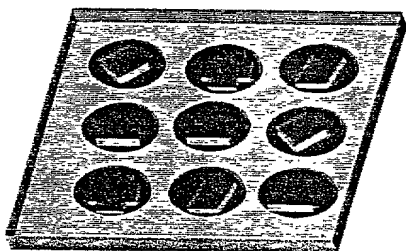


FIG. 8A

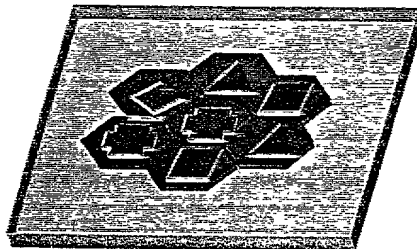


FIG. 8B

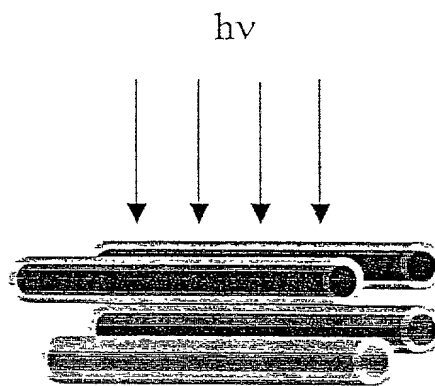


FIG. 9A

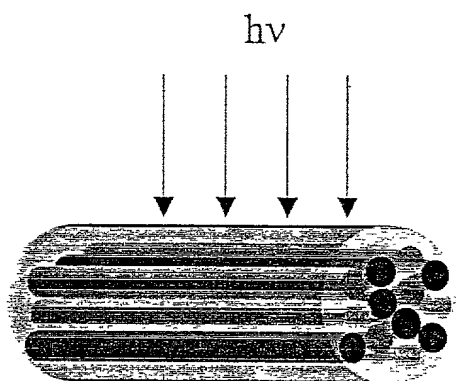


FIG. 9B

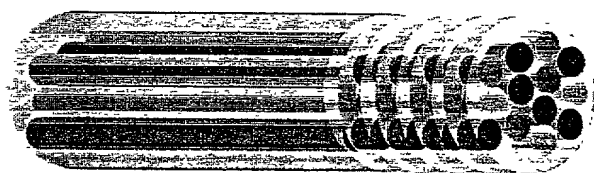


FIG. 9C

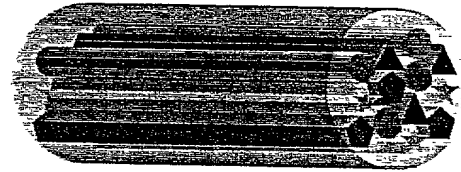
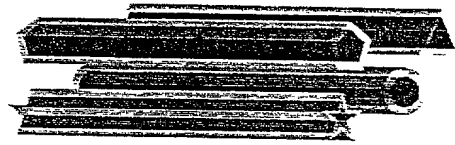


FIG. 10

20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52 53 54 55 56 57 58 59 60 61 62 63 64 65 66 67 68 69 70 71 72 73 74 75 76 77 78 79 80 81 82 83 84 85 86 87 88 89 90 91 92 93 94 95 96 97 98 99 100



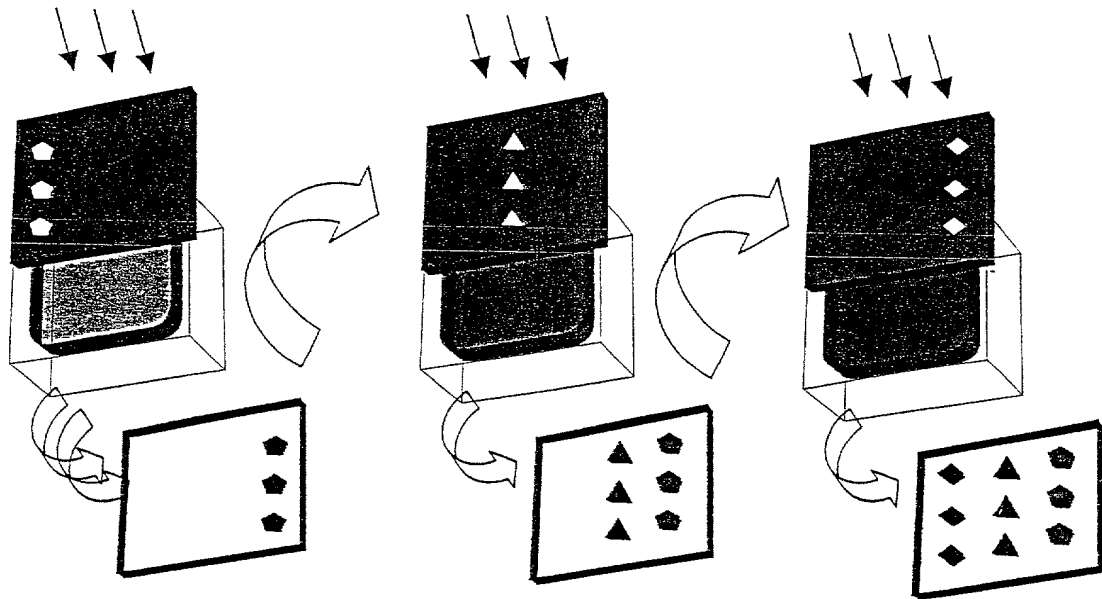


FIG. 11

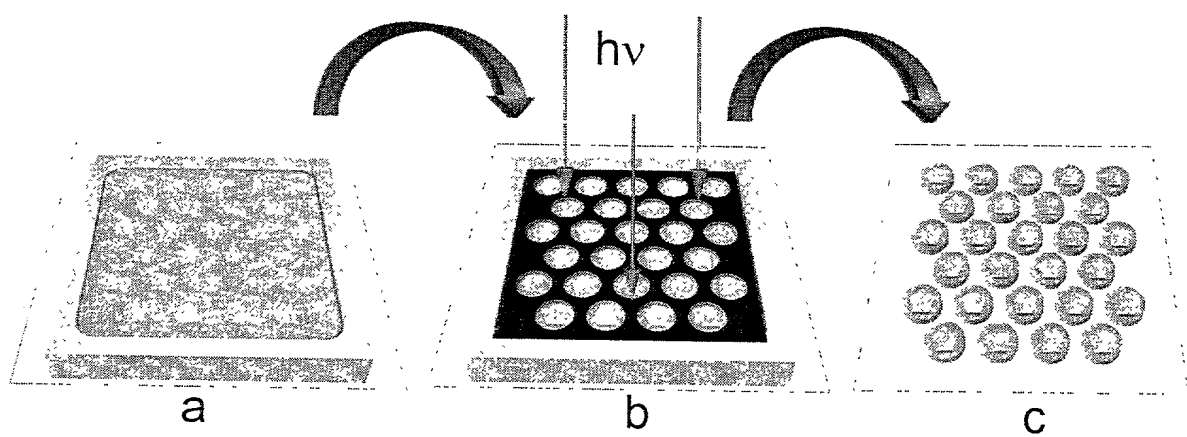
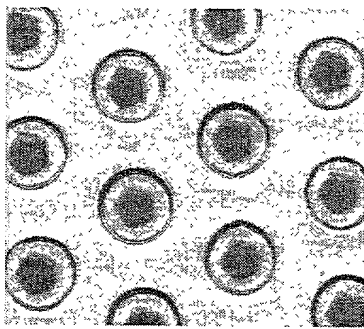
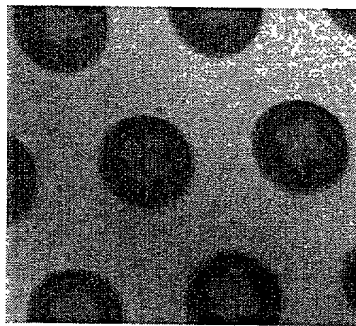


FIG. 12



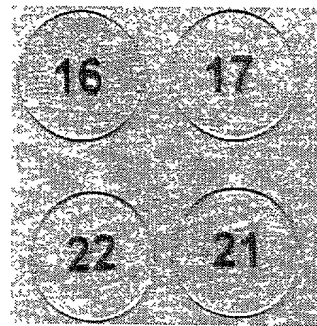
2.5mm

A



2mm

B



5mm

C

FIG. 13

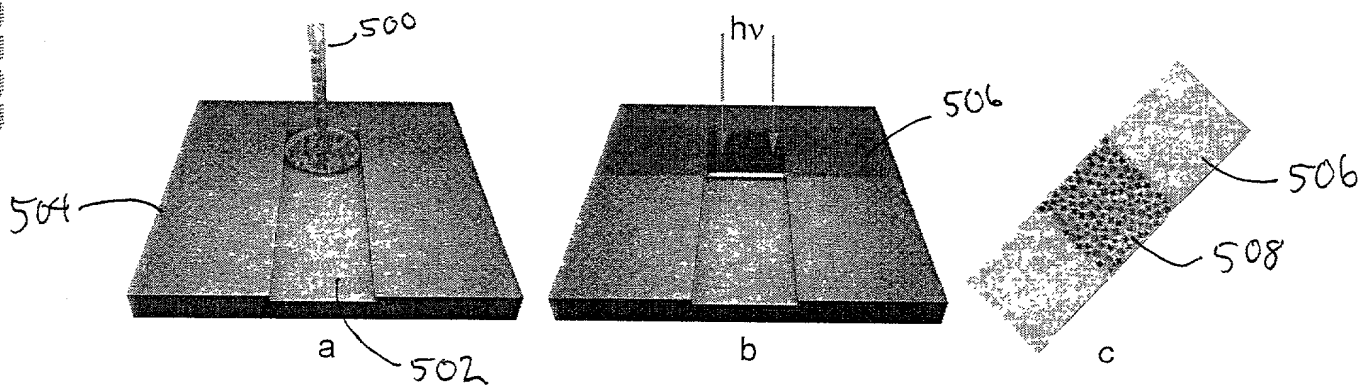


FIG. 14

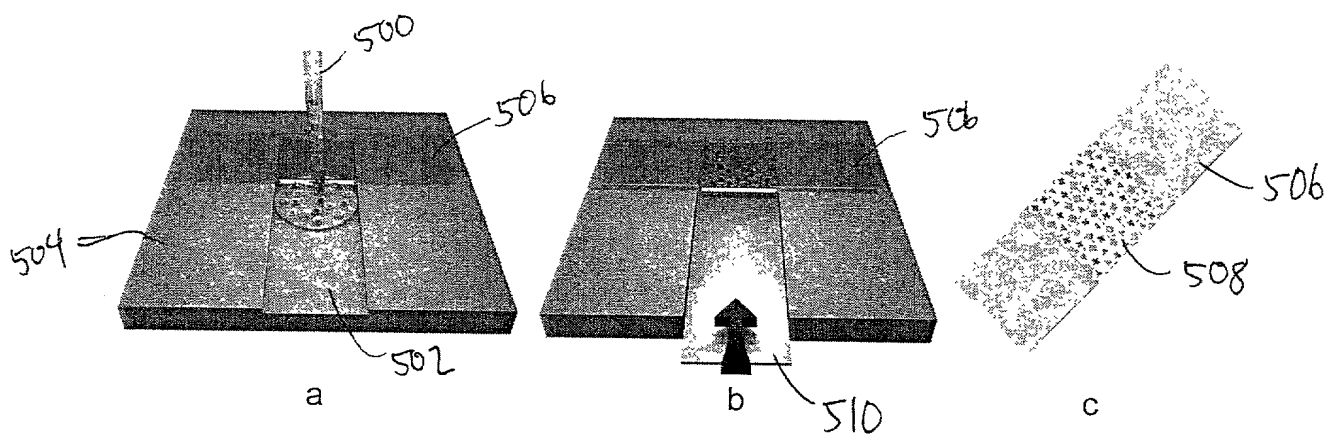
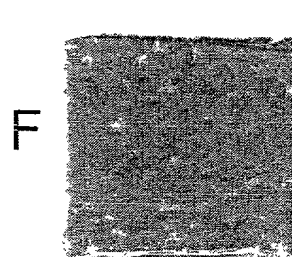
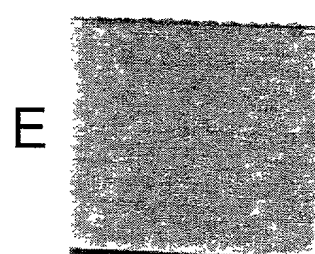
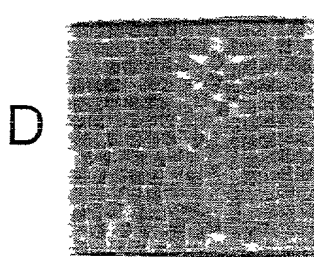
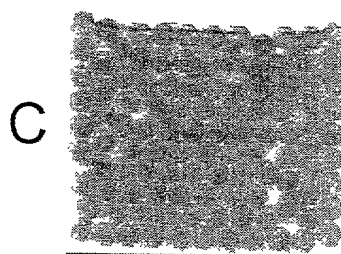
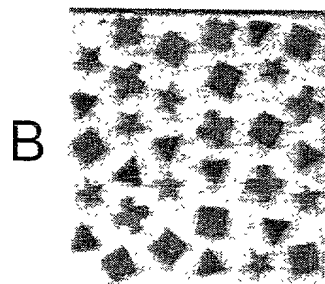
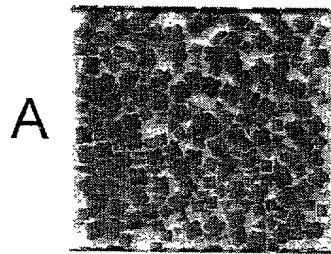


FIG. 15

FIG. 16



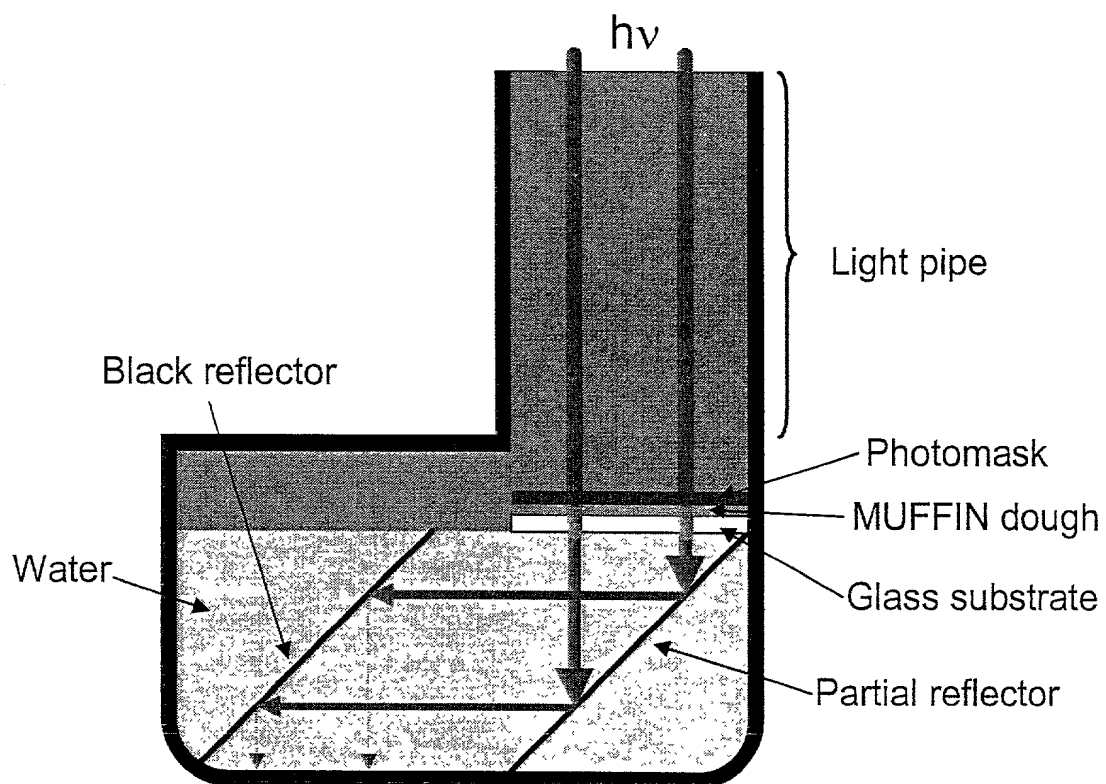


FIG. 17